

Number of Components:	Two	Minimum Bond Line Cure Schedule*:	
Mix Ratio By Weight:	1:1	150°C	1 Hour
Specific Gravity:			
Part A	1.29		
Part B	1.33		
Pot Life:	24 Hours		
Shelf Life:	One year at room temperature		

Note: Container(s) should be kept closed when not in use. \*Please see Applications Note available on our website.

### Product Description:

EPO-TEK<sup>®</sup> 377H is a two component, high Tg, graphite filled epoxy designed for ESD/EMI shielding of semiconductor devices and electronics. It can be used in many electronic industries like consumer, military, medical, and optical / OEM / fiber optics. It is an electrically conductive version of EPO-TEK<sup>®</sup> 377.

### EPO-TEK<sup>®</sup> 377H Advantages & Application Notes:

- Low viscosity - ideal for commercial and micro-dispensing applications.
- Suggested applications:
  - Opto-electronics: Adhering IR filter windows to cap of TO-can; opaque epoxy resin in IR and VIS range; near hermetic sealing of windows and packages.
  - Hybrid Microelectronics: adhesion to kovar, stainless steel, ceramics, glasses, lids or substrates in Rf/Microwave devices.
- Convenient 1:1 mix ratio allows for static mixing, or specialty packaging in double-barrel syringes.

**Typical Properties:** (To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 150°C/1 hour; \* denotes test on lot acceptance basis)

Physical Properties:	
*Color: Part A: Black Part B: Black	Die Shear Strength @ 23°C: ≥ 10 Kg / 3,400 psi
*Consistency: Pourable liquid	Degradation Temp. (TGA): 345°C
*Viscosity (@ 100 RPM/23°C): 500 – 1,000 cPs	Weight Loss:
Thixotropic Index: N/A	@ 200°C: 0.09%
*Glass Transition Temp.(Tg): ≥ 95°C (Dynamic Cure	@ 250°C: 0.66%
20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)	@ 300°C: 0.78%
Coefficient of Thermal Expansion (CTE):	Operating Temp:
Below Tg: 56 x 10 <sup>-6</sup> in/in/°C	Continuous: - 55°C to 175°C
Above Tg: 200 x 10 <sup>-6</sup> in/in/°C	Intermittent: - 55°C to 275°C
Shore D Hardness: 80	Storage Modulus @ 23°C: 416,850psi
Lap Shear Strength @ 23°C: > 2,000psi	*Particle Size: ≤ 40 Microns
Optical Properties @ 23°C:	
Index of Refraction: N/A	Spectral Transmission: < 0.1 % @ 400 - 1500 nm
Electrical & Thermal Properties:	
Thermal Conductivity: 0.44 W/mK	Volume Resistivity @ 23°C: ≥ 400 Ohm-cm
Dielectric Constant (1KHz): N/A	Dissipation Factor (1KHz): N/A

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